UNITRODE

UC1901
UC2901
UC3901

Isolated Feedback Generator

FEATURES

- An Amplitude-Modulation System for Transformer Coupling an Isolated Feedback Error Signal
- Low-Cost Alternative to Optical Couplers
- Internal 1% Reference and Error Amplifier
- Internal Carrier Oscillator Usable to 5MHz
- Modulator Synchronizable to an External Clock
- Loop Status Monitor

DESCRIPTION

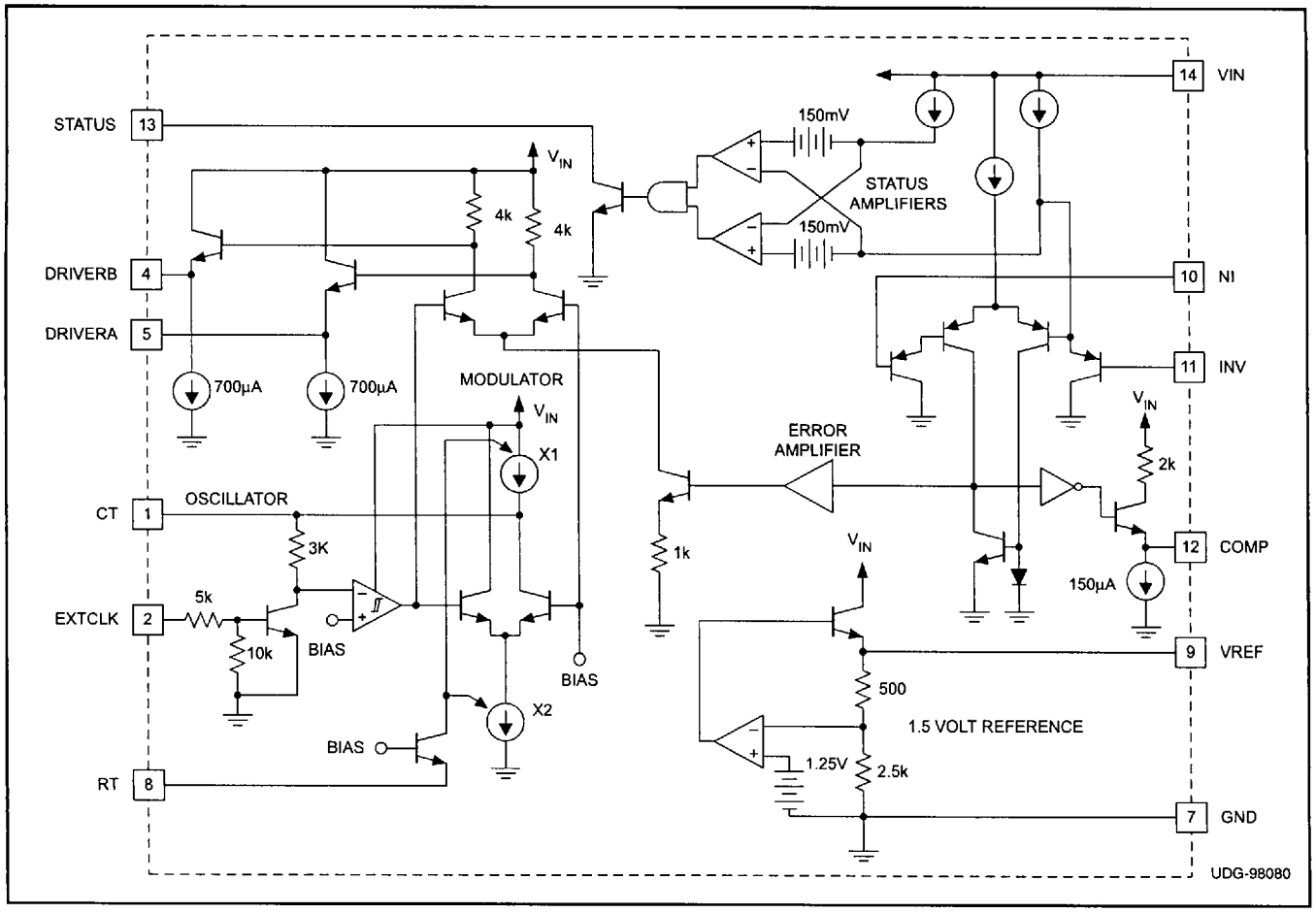
The UC1901 family is designed to solve many of the problems associated with closing a feedback control loop across a voltage isolation boundary. As a stable and reliable alternative to an optical coupler, these devices feature an amplitude modulation system which allows a loop error signal to be coupled with a small RF transformer or capacitor.

The programmable, high-frequency oscillator within the UC1901 series permits the use of smaller, less expensive transformers which can readily be built to meet the isolation requirements of today's line-operated power systems. As an alternative to RF operation, the external clock input to these devices allows synchronization to a system clock or to the switching frequency of a SMPS.

An additional feature is a status monitoring circuit which provides an active-low output when the sensed error voltage is within ±10% of the reference. The DRIVERA output, DRIVERB output, and STATUS output are disabled until the input supply has reached a sufficient level to allow proper operation of the device.

Since these devices can also be used as a DC driver for optical couplers, the benefits of 4.5 to 40V supply operation, a 1% accurate reference, and a high gain general purpose amplifier offer advantages even though an AC system may not be desired.

UC1901 SIMPLIFIED SCHEMATIC



ABSOLUTE MAXIMUM RATINGS *(Note 1)*

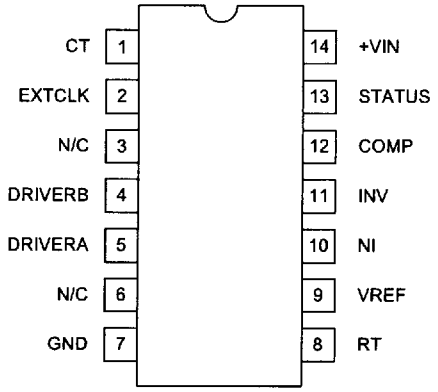
Input Supply Voltage, V_{IN} 40V
Reference Output Current . . . . . –10mA
Driver Output Currents . . . . . –35mA
Status Indicator Voltage 40V
Status Indicator Current 20mA
Ext. Clock Input 40V
Error Amplifier Inputs . . . . . –0.5V to +35V
Power Dissipation at T_A = 25°C 1000mW
Power Dissipation at T_C = 25°C 2000mW
Operating Junction Temperature . . . . . –55°C to +150°C
Storage Temperature . . . . . –65°C to +150°C
Lead Temperature (Soldering, 10 seconds) . . . . . 300°C

Note 1: *Voltages are referenced to ground, Pin 7. Currents are positive into, negative out of the specified terminal.*

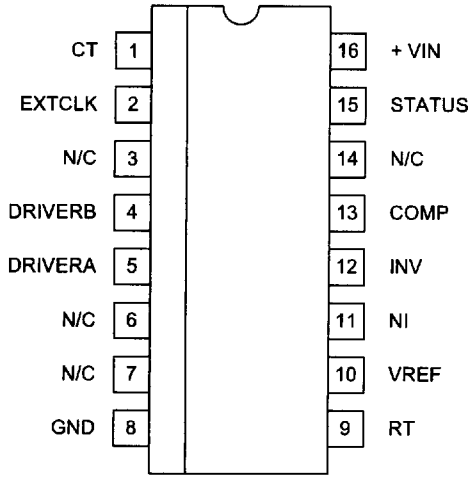
Note 2: *Consult Packaging section of Databook for thermal limitations and considerations of package.*

CONNECTION DIAGRAMS

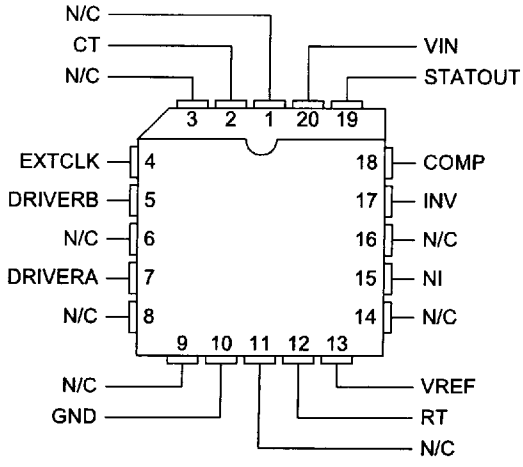
DIL-14, SOIC-14 (TOP VIEW)
J or N Package, D Package



SOIC-16 Wide (TOP VIEW)
DW Package



PLCC-20, LCC-20 (TOP VIEW)
Q, L Packages



TEMPERATURE AND PACKAGE SELECTION GUIDE

	TEMPERATURE RANGE	AVAILABLE PACKAGES
UC1901	–55°C to +125°C	J, L
UC2901	–40°C to +85°C	D, DW, J, N, Q
UC3901	0°C to +70°C	D, DW, J, N, Q

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for V_{IN} = 10V, R_T = 10kΩ, C_T = 820pF, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	UC1901/UC2901			UC3901			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Reference Section								
Output Voltage	T_J = 25°C	1.485	1.5	1.515	1.47	1.5	1.53	V
	$T_{MIN} \le T_J \le T_{MAX}$	1.470	1.5	1.530	1.455	1.5	1.545	
Line Regulation	V_{IN} = 4.5 to 35V		2	10		2	15	mV
Load Regulation	I_{OUT} = 0 to 5mA		4	10		4	15	mV
Short Circuit Current	T_J = 25°C		–35	–55		–35	–55	mV
Error Amplifier Section (To Compensation Terminal)								
Input Offset Voltage	V_{CM} = 1.5V		1	4		1	8	mV
Input Bias Current	V_{CM} = 1.5V		–1	–3		–1	–6	µA
Input Offset Current	V_{CM} = 1.5V		0.1	1		0.1	2	µA
Small Signal Open Loop Gain		40	60		40	60		dB
CMRR	V_{CM} = 0.5 to 7.5V	60	80		60	80		dB
PSRR	V_{IN} = 2 to 25V	80	100		80	100		dB
Output Swing, Δ Vo		0.4	0.7		0.4	0.7		V
Maximum Sink Current		90	150		90	150		µA
Maximum Source Current		–2	–3		–2	–3		mA
Gain Band Width Product			1			1		MHz
Slew Rate			0.3			0.3		V/µS
Modulators/Drivers Section (From Compensation Terminal)								
Voltage Gain		11	12	13	10	12	14	dB
Output Swing		±1.6	±2.8		±1.6	±2.8		V
Driver Sink Current		500	700		500	700		µA
Driver Source Current		–15	–35		–15	–35		mA
Gain Band Width Product			25			25		MHz
Oscillator Section								
Initial Accuracy	T_J = 25°C	140	150	160	130	150	170	kHz
	$T_{MIN} \le T_J \le T_{MAX}$	130		170	120		180	kHz
Line Sensitivity	V_{IN} = 5 to 35V		.15	.35		.15	.60	%/V
Maximum Frequency	R_T = 10k, C_T = 10pF		5			5		MHz
Ext. Clock Low Threshold	Pin 1 (C_T) = V_{IN}	0.5			0.5			V
Ext. Clock High Threshold	Pin 1 (C_T) = V_{IN}			1.6			1.6	V
Status Indicator Section								
Input Voltage Window	@ E/A Inputs, V_{CM} = 1.5V	±135	±150	±165	±130	±150	±170	mV
Saturation Voltage	E/A Δ Input = 0V, I_{SINK} = 1.6mA			0.45			0.45	V
Max. Output Current	Pin 13 = 3V, E/A Δ Input = 0.0V	8	15		8	15		mA
Leakage Current	Pin 13 = 40V, E/A ΔInput = 0.2V		.05	1		.05	5	µA
Supply Current	V_{IN} = 35V		5	8		5	10	mA
UVLO Section								
Drivers Enabled Threshold	At Input Supply V_{IN}		3.9	4.5		3.9	4.5	V
Status Output Enabled Threshold	At Input Supply V_{IN}		3.9	4.5		3.9	4.5	V
Change in Reference Output	When V_{IN} Reaches UVLO Threshold		–2	–30		–2	–30	mV

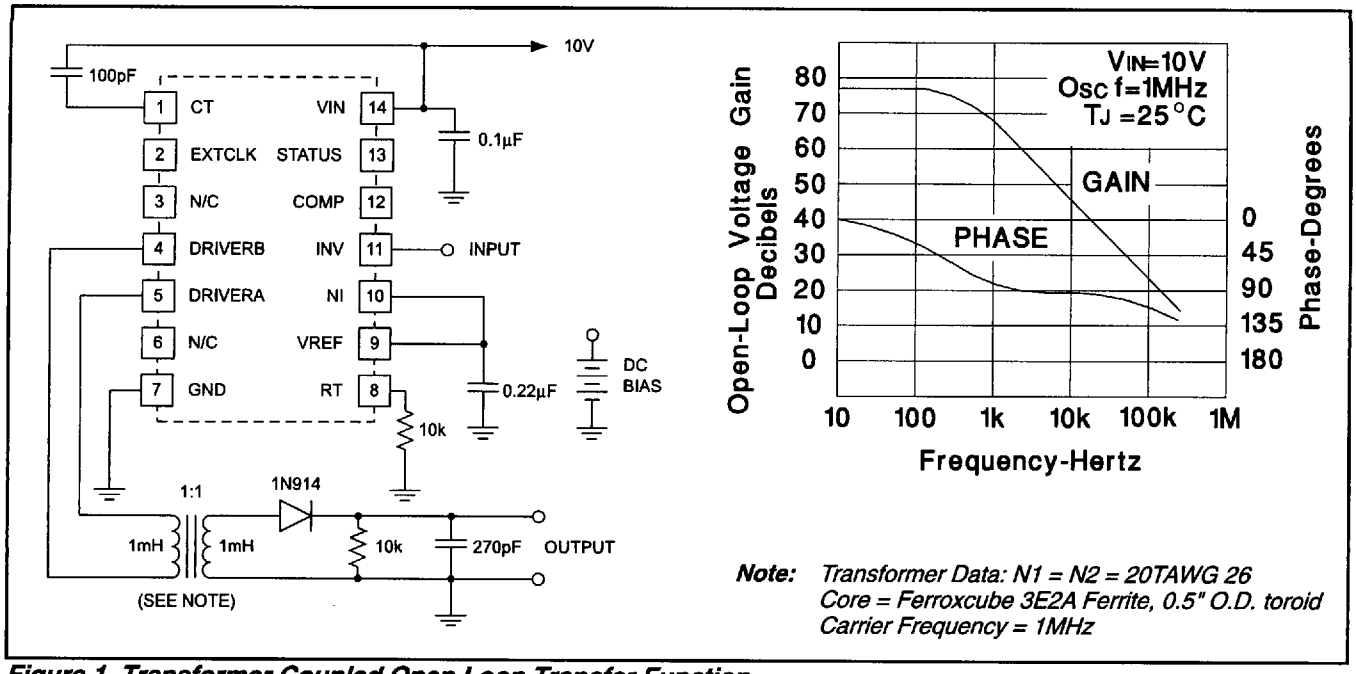


Figure 1. Transformer Coupled Open Loop Transfer Function

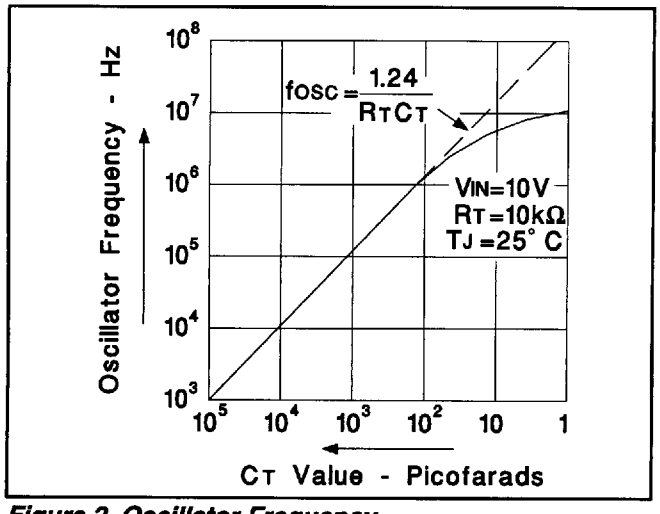


Figure 2. Oscillator Frequency

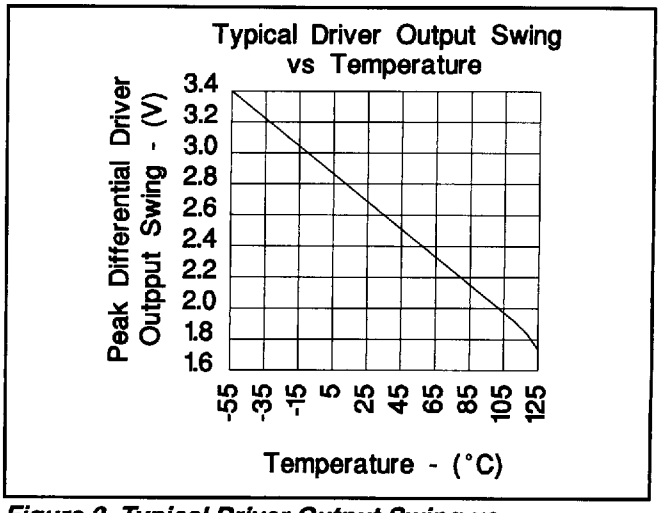


Figure 3. Typical Driver Output Swing vs Temperature

APPLICATION INFORMATION

The error amplifier compensation terminal, Pin 12, is intended as a source of feedback to the amplifier's inverting input at Pin 11. For most applications, a series DC blocking capacitor should be part of the feedback network. The amplifier is internally compensated for unity feedback.

The waveform at the driver outputs is a squarewave with an amplitude that is proportional to the error amplifier input signal. There is a fixed 12dB of gain from the error amplifier compensation pin to the modulator driver outputs. The frequency of the output waveform is controlled by either the internal oscillator or an external clock signal.

With the internal oscillator the squarewave will have a fixed 50% duty cycle. If the internal oscillator is disabled by connecting Pin 1, C_R, to V_{IN} then the frequency and duty cycle of the output will be determined by the input clock waveform at Pin 2. If the oscillator remains disabled and there is not clock input at Pin 2, there will be a linear 12dB of signal gain to one or the other of the driver outputs depending on the DC state of Pin 2.

The driver outputs are emitter followers which will source a minimum of 15mA of current. The sink current, internally limited at 700µA, can be increased by adding resistors to ground at the driver outputs.

APPLICATION INFORMATION (continued)

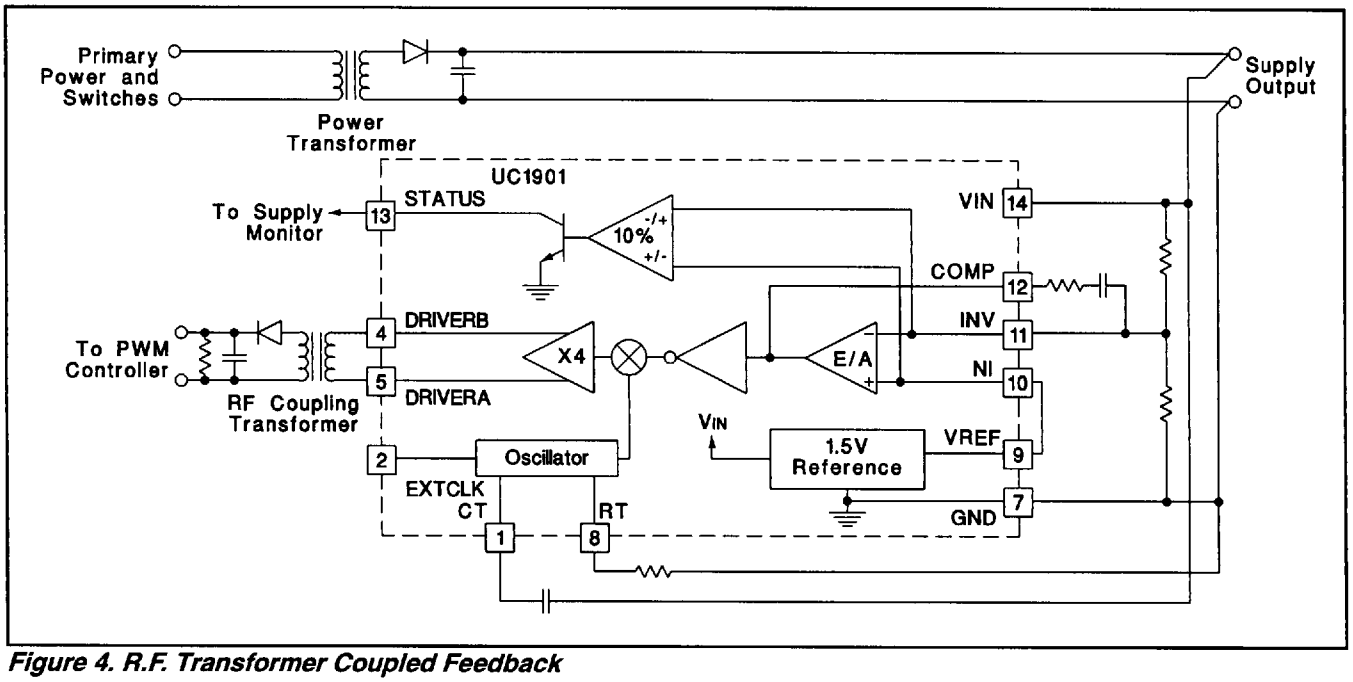


Figure 4. R.F. Transformer Coupled Feedback

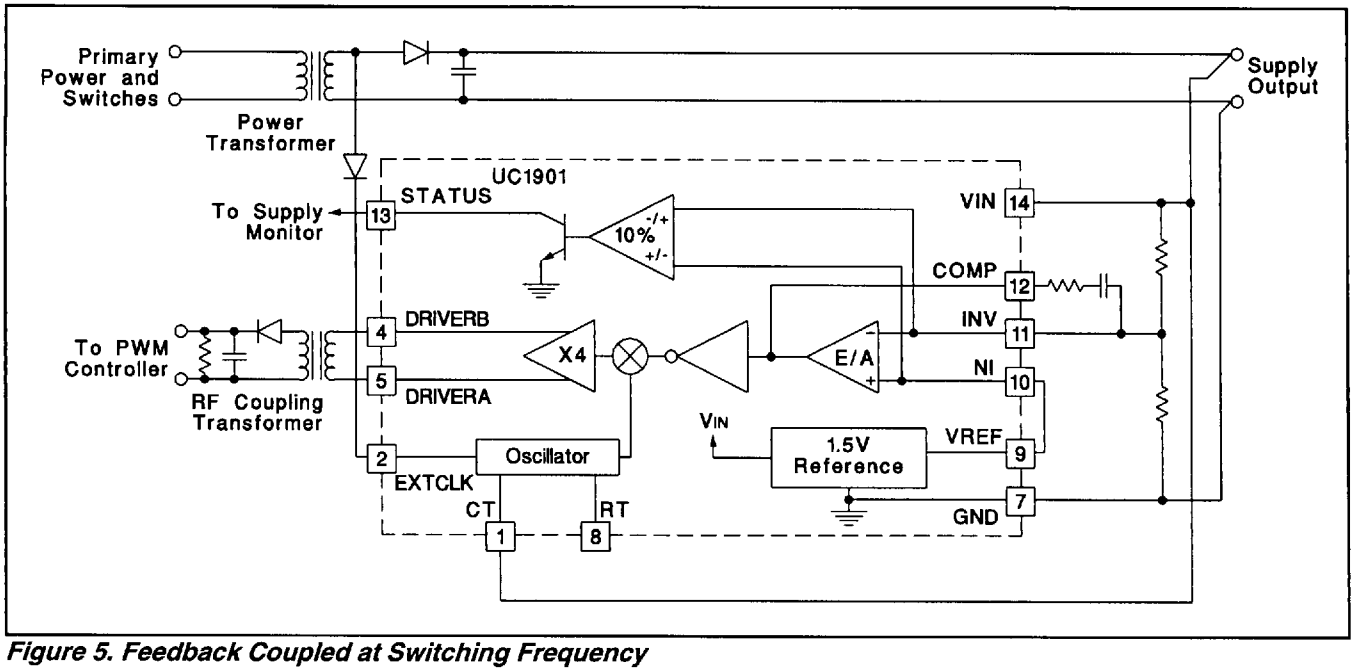


Figure 5. Feedback Coupled at Switching Frequency

TYPICAL APPLICATION

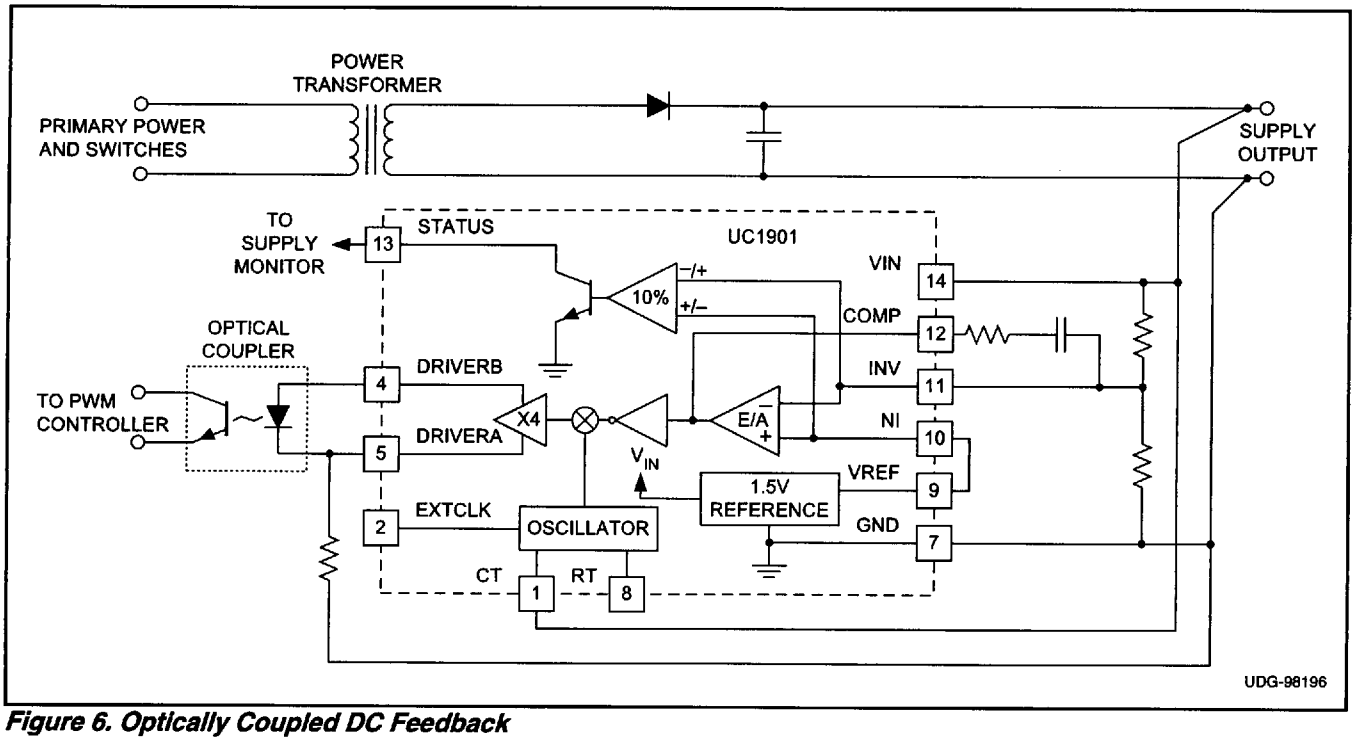


Figure 6. Optically Coupled DC Feedback

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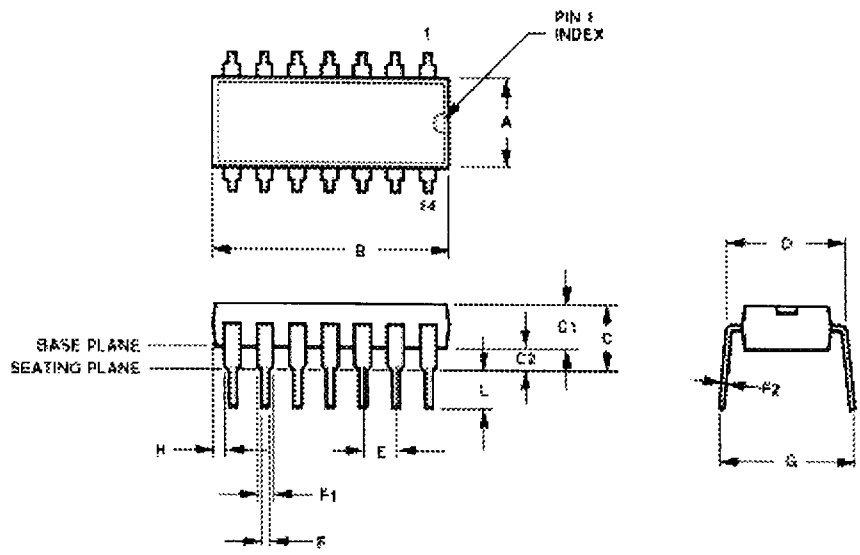
14-PIN PLASTIC DIP ~ N PACKAGE SUFFIX

DIMENSIONS					
	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	.245	.260	6.22	6.60	1
B	.745	.775	18.92	19.68	1
C	-	.210	-	5.33	
C1	.125	.150	3.18	3.81	
C2	.015	.055	0.38	1.40	2
D	.300	.325	7.62	8.26	3
E	.100 BSC		2.54 BSC		4
F	.014	.022	0.35	0.56	
F1	.045	.070	1.14	1.78	
F2	.008	.014	0.20	0.35	
G	.300	.400	7.62	10.16	5
H	.005	-	0.13	-	
L	.115	.160	2.92	4.06	



NOTES:

1. 'A' AND 'B' DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 IN. PER SIDE.
2. 'C2' SHALL BE MEASURED FROM THE SEATING PLANE TO THE BASE PLANE.
3. 'D' SHALL BE MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO THE BASE PLANE.
4. 'THE BASIC LEAD SPACING IS 0.100 IN. BETWEEN CENTERLINES. EACH LEAD CENTERLINE SHALL BE LOCATED WITHIN ±0.010 IN. OF ITS EXACT TRUE POSITION.
5. 'G' SHALL BE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
6. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.

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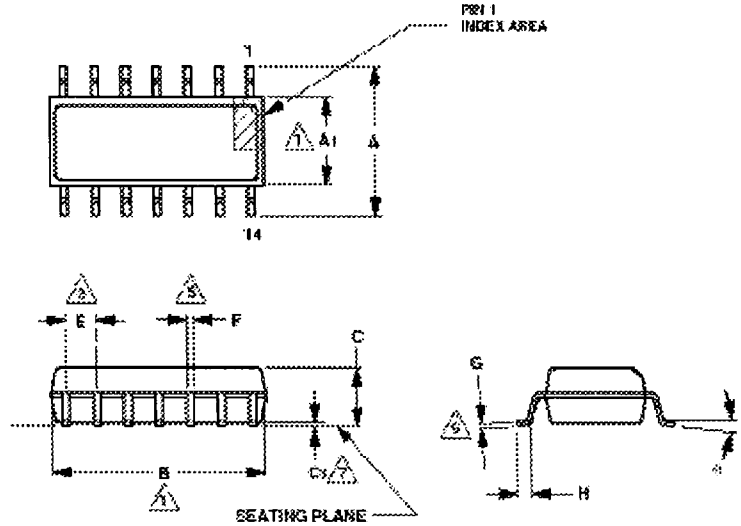
14-PIN SOIC SURFACE MOUNT~ D, PACKAGE SUFFIX

DIMENSIONS				
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.228	.244	5.80	6.20
A1	.150	.158	3.80	4.00
B	.336	.344	8.55	8.75
C	.053	.069	1.35	1.75
C1	.004	.009	0.10	0.22
E	.050 BSC		1.27 BSC	
F	.014	.019	0.36	0.48
G	.007	.010	0.19	0.25
H	.016	.035	0.41	0.89
θ	0°	8°	0°	8°



NOTES:

1. 'A1' AND 'B' DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 IN. PER SIDE.
2. LEADS SHALL BE COPLANAR WITHIN 0.004 IN. AT THE SEATING PLANE.
3. THE BASIC LEAD SPACING IS 0.050 IN. BETWEEN CENTERLINES. EACH LEAD CENTERLINE SHALL BE LOCATED WITHIN ±0.004 IN. OF ITS EXACT TRUE POSITION.
4. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.
5. DIMENSION 'F' DOES NOT INCLUDE DAMBAR PROTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 'F' MAXIMUM BY MORE THAN 0.003 IN. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
6. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.004 IN. AND 0.010 IN. FROM THE LEAD TIP.
7. 'C1' IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY (BASE PLANE).

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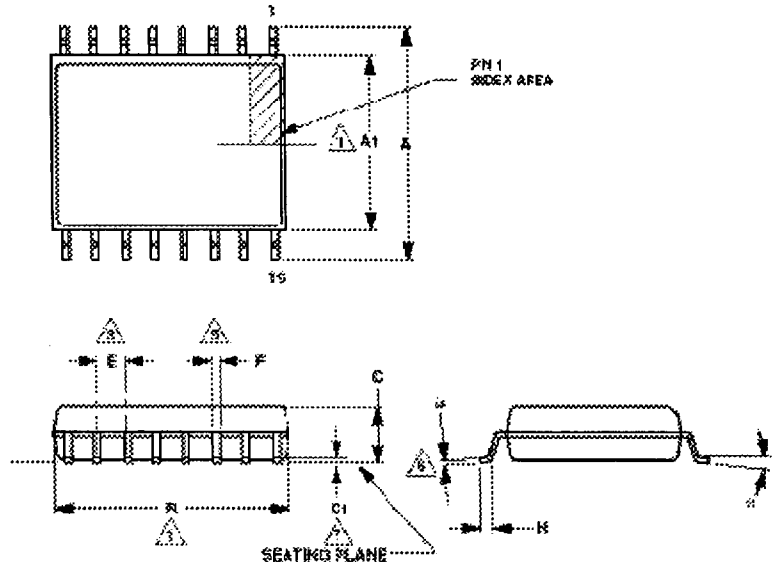
16-PIN SOIC SURFACE MOUNT~ DW PACKAGE SUFFIX

DIMENSIONS				
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.394	.419	10.00	10.64
A1	.292	.299	7.42	7.59
B	.403	.413	10.24	10.49
C	.097	.104	2.48	2.64
C1	.004	.011	0.10	0.28
E	.050 BSC		1.27 BSC	
F	.014	.019	0.36	0.48
G	.009	.012	0.23	0.30
H	.018	.035	0.46	0.89
θ	0°	8°	0°	8°



NOTES:

1. 'A1' AND 'B' DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 IN. PER SIDE.
2. LEADS SHALL BE COPLANAR WITHIN 0.004 IN. AT THE SEATING PLANE.
3. THE BASIC LEAD SPACING IS 0.050 IN. BETWEEN CENTERLINES. EACH LEAD CENTERLINE SHALL BE LOCATED WITHIN ±0.004 IN. OF ITS EXACT TRUE POSITION.
4. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.
5. DIMENSION 'F' DOES NOT INCLUDE DAMBAR PROTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 'F' MAXIMUM BY MORE THAN 0.003 IN. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
6. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.004 IN. AND 0.010 IN. FROM THE LEAD TIP.
7. 'C1' IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY (BASE PLANE).

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Mechanical Drawings

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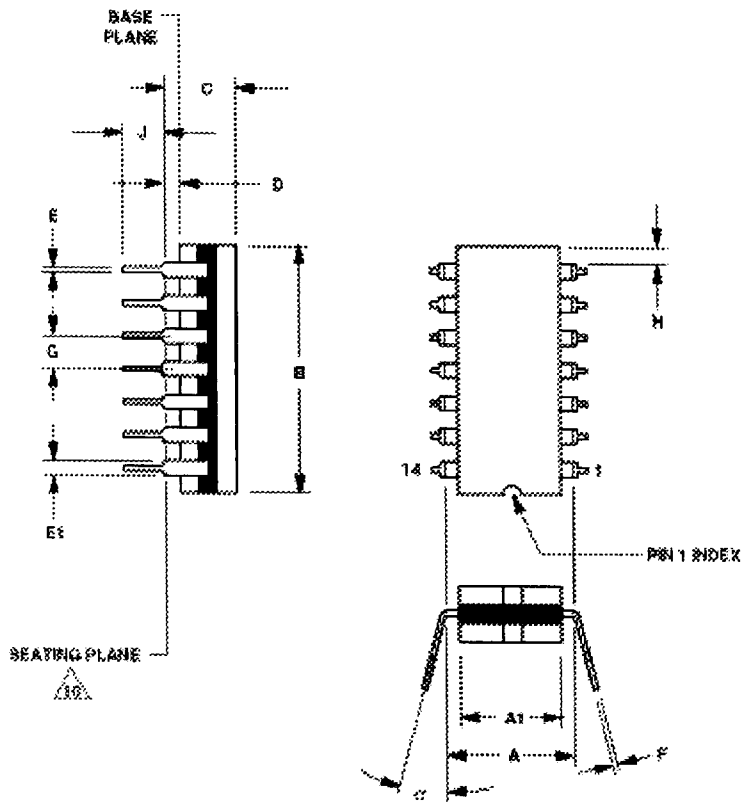
14-PIN CERAMIC DIP ~ J PACKAGE SUFFIX

DIMENSIONS					
	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.290	0.320	7.37	8.13	7
A1	0.220	0.310	5.59	7.87	4
B	-	0.785	-	19.94	4
C	-	0.200	-	5.08	
D	0.015	0.060	0.38	1.52	3
E	0.014	0.026	0.36	0.66	8
E1	0.045	0.065	1.14	1.65	2
F	0.008	0.018	0.20	0.46	8
G	0.100 BSC		2.54 BSC		5
H	0.005	-	0.13	-	6
J	0.125	0.200	3.18	5.08	
α	0°	15°	0°	15°	



NOTES:

1. INDEX AREA: A NOTCH OR A PIN ONE IDENTIFICATION MARK SHALL BE LOCATED ADJACENT TO PIN ONE. THE MANUFACTURER'S IDENTIFICATION SHALL NOT BE USED AS A PIN ONE IDENTIFICATION MARK.
2. THE MINIMUM LIMIT FOR DIMENSION 'E1' MAY BE 0.023 (0.58mm) FOR LEADS NUMBER 1, 7, 8 AND 14 ONLY.
3. DIMENSION 'D' SHALL BE MEASURED FROM THE SEATING PLANE TO THE BASE PLANE.
4. THIS DIMENSION ALLOWS FOR OFF-CENTER LID, MENISCUS AND GLASS OVERRUN.
5. THE BASIC PIN SPACING IS 0.100 (2.54mm) BETWEEN CENTERLINES. EACH PIN CENTERLINE SHALL BE LOCATED WITHIN ±0.010 (0.25mm) OF ITS EXACT TRUE POSITION.
6. APPLIES TO ALL FOUR CORNERS (LEADS NUMBER 1, 7,8 AND 14).
7. DIMENSION 'A' SHALL BE MEASURED AT THE CENTERLINE OF THE LEADS WHEN $\alpha = 0°$.
8. THE MAXIMUM LIMITS OF DIMENSIONS 'E' AND 'F' SHALL BE MEASURED AT THE CENTER OF THE FLAT WHEN SOLDER DIP IS APPLIED.
9. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.
10. THE SEATING PLANE IS LOCATED AT THE LOWEST POINT ON THE LEAD AT

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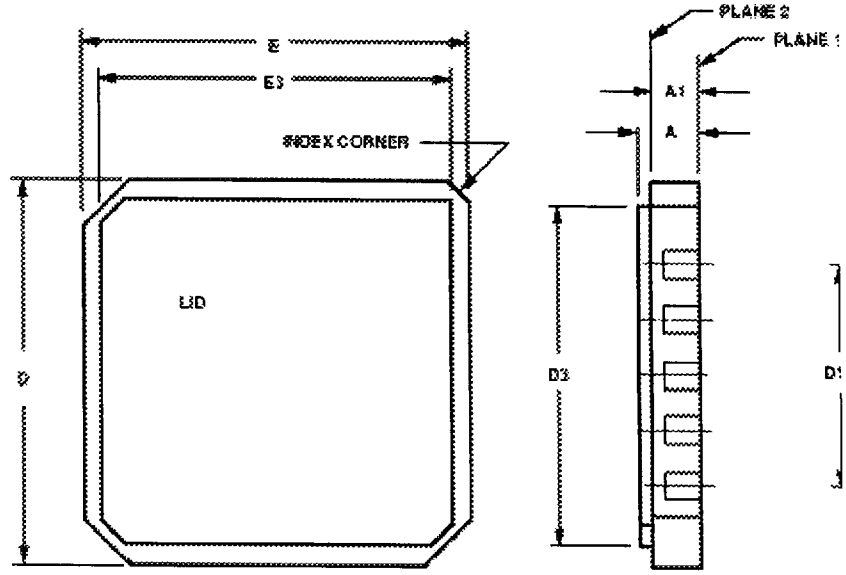
20-PIN CERAMIC LEADLESS SURFACE MOUNT ~ L PACKAGE SUFFIX

DIMENSIONS					
	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	.060	.100	1.52	2.54	6
A1	.050	.088	1.27	2.24	
B1	.022	.028	0.56	0.71	1,3
B2	.072 REF.		1.83 REF.		
B3	.006	.022	0.15	0.56	8
D/E	.342	.358	8.69	9.09	
D1/E1	.200 BSC		5.08 BSC		
D2/E2	.100 BSC		2.54 BSC		
D3/E3	-	.358	-	9.09	4
L	.045	.055	1.14	1.40	
L1	.045	.055	1.14	1.40	
L2	.075	.095	1.90	2.41	5
L3	.003	.015	0.08	0.38	
N	20		20		2
ND/NE	5		5		2
e	.050 BSC		1.27 BSC		10



NOTES:

1. A MINIMUM CLEARANCE OF 0.015 IN. (0.38mm) SHALL BE MAINTAINED BETWEEN ADJACENT TE
2. 'N' IS THE MAXIMUM QUANTITY OF TERMINAL POSITIONS. 'ND' AND 'NE' ARE THE NUMBERS OF AND 'E' RESPECTIVELY.
3. ELECTRICAL CONNECTION TERMINALS ARE REQUIRED ON PLANE 1 AND OPTIONAL ON PLANE THEY SHALL BE ELECTRICALLY CONNECTED TO OPPOSING TERMINALS ON PLANE 1.
4. A MINIMUM CLEARANCE OR 0.015 IN. (0.38mm) SHALL BE MAINTAINED BETWEEN A METAL LID TERMINALS, METALLIZED CASTELLATIONS, ETC.) THE LID SHALL NOT EXTEND BEYOND THE E
5. THE INDEX FEATURE FOR NUMBER 1 TERMINAL IDENTIFICATION, OPTIONAL ORIENTATION OR AREA DEFINED BY DIMENSIONS 'B2' AND 'L2' ON PLANE 1.
6. DIMENSION 'A' CONTROLS THE OVERALL PACKAGE THICKNESS.
7. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.
8. CASTELLATIONS ARE REQUIRED ON BOTTOM TWO LAYERS. CASTELLATIONS IN THE TOP LAYE
9. WHEN SOLDER DIP LEAD FINISH APPLIES, SOLDER BUMP HEIGHT SHALL NOT EXCEED 0.007 INC NOT EXCEED 0.006 INCHES.
10. THE BASIC TERMINAL SPACING IS 0.050 INCHES BETWEEN CENTERLINES. EACH TERMINAL CEN INCHES OF ITS EXACT TRUE POSITION.

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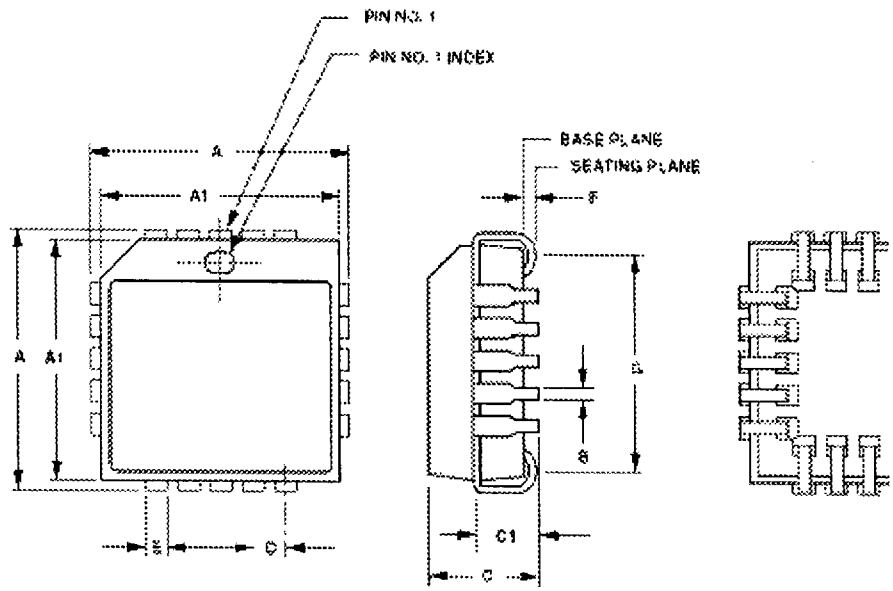
20-PIN PLASTIC PLCC SURFACE MOUNT~ Q PACKAGE SUFFIX

DIMENSIONS					
	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	.385	.395	9.78	10.03	
A1	.350	.356	8.89	9.04	1
B	.013	.021	0.33	0.53	
C	.170	.180	4.32	4.57	
C1	.100	.110	2.54	2.79	
D	.050 BSC		1.27 BSC		2
E	.026	.032	0.66	0.81	
F	.020	-	0.51	-	3, 4
G	.290	.330	7.37	8.38	



NOTES:

1. 'A1' DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 IN. PER SIDE.
2. THE BASIC LEAD SPACING IS 0.050 IN. BETWEEN CENTERLINES. EACH LEAD CENTERLINE SHALL LOCATED WITHIN ±0.004 IN. OF ITS EXACT TRUE POSITION.
3. 'F' IS MEASURED FROM THE SEATING PLANE TO THE BASE PLANE.
4. LEADS SHALL BE COPLANAR WITHIN 0.004 IN. AT THE SEATING PLANE.
5. CONTROLLING DIMENSION: INCHES. MILLIMETERS SHOWN FOR REFERENCE ONLY.